

02-21-2002



P/1071-1523

PATENTS

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SHEET

To the Assistant Commissioner of Patents and Trademarks: Please record the attached original document or copy thereof.

1. Name of conveying party(ies):

Masaaki KANAE

2-8-02

Type of Entity: Individual

Additional names(s) of conveying party(ies) attached? No

2. Name and Address of receiving party(ies):

Murata Manufacturing Co., Ltd.  
Dept. A170  
26-10, Tenjin 2-chome  
Nagaokakyo-shi, Kyoto-fu 617-8555  
JAPAN

Type of Entity: Corporation-Japanese

Additional name(s) &amp; address(es) attached? No

3. Nature of Conveyance:

Assignment

Execution Date: January 21, 2002

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: January 21, 2002

A. Application No.(s)

10,072679

B. Patent No.(s)

Additional numbers attached? No

5. Name and address of party to whom correspondence concerning document should be mailed:

OSTROLENK, FABER, GERB & SOFFEN, LLP  
1180 Avenue of the Americas  
New York, New York 10036-8403

6. Total number of documents involved: One

7. Total fee (37 CFR 3.41): \$ 40.00

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8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

James A. Finder

Name of Person Signing

Signature

February 8, 2002

Date

Total number of pages including cover sheet, attachments, and document: 2

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PATENT  
REEL: 012586 FRAME: 0827

PATENT APPLICATION ASSIGNMENT -

OFGS FILE NO. P/1071-1523

WHEREAS, I, **Masaaki KANAE** as assignor, have invented certain improvements in **SEMICONDUCTOR CHIP PRODUCTION METHOD AND SEMICONDUCTOR WAFER** for which an application for United States Letters Patent has been executed by me of even date herewith; and

WHEREAS, **Murata Manufacturing Co., Ltd., Dept. A170, 26-10, Tenjin 2-chome, Nagaokakyo-shi, Kyoto-fu 617-8555**, as assignee, is desirous of acquiring all right, title and interest in and to said invention and any Patent that may be granted therefor.

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, I, as assignor, hereby sell, assign and set over to said assignee the entire right, title and interest for the United States and all other countries in and to said invention and the aforesaid application for Patent, all original, divisional, continuation, substitute or reissue applications and patents applied for or granted therefor in the United States and all other countries, including all rights of priority from the filing of said application, and all rights for past infringement, and the Commissioner of Patents and Trademarks is hereby authorized and requested to issue all patents on said inventions or resulting therefrom to said assignee herein, as assignee of the entire interest therein; and the undersigned for myself and my legal representatives, heirs and assigns do hereby agree and covenant without further remuneration, to execute and deliver all divisional, continuation, reissue and other applications for Patent on said inventions and all assignments thereof to said assignee or its assigns, to communicate to said assignee or its representatives all facts known to the undersigned respecting said inventions, whenever requested, to testify in any interferences or other legal proceedings in which any of said applications or patents may become involved, to sign all lawful papers, make all rightful oaths, and to do generally everything necessary to assist assignee, its successors, assigns and nominees to obtain patent protection for said invention in the United States and all other countries, the expenses incident to said applications to be borne and paid by said assignee.

Date:

1 / 21 / 2002

Masaaki KANAE  
Masaaki KANAE

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